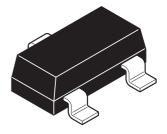


2N7002 60V SOT23 N-channel enhancement mode MOSFET

Summary

| V _{(BR)DSS} | $R_{DS(on)}$ (Ω) | I _D (A) | |
|----------------------|-----------------------------|--------------------|--|
| 60 | 7.5 @ V _{GS} = 10V | 0.5 | |
| | 7.5 @ V _{GS} = 5V | 0.05 | |

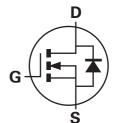


Description

A small signal MOSFET for general purpose switching applications.

Features

- · Fast switching speed
- · Low gate drive capability
- SOT23 package

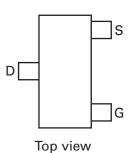


Applications

· General switching applications

Ordering information

| Device | Reel size (inches) | Tape width (mm) | Quantity per reel |
|--------|-----------------------|--------------------|-------------------|
| 2N7002 | 7 | 8 | 3,000 |



Device marking

702

Absolute maximum ratings

| Parameter | Symbol | Limit | Unit |
|--|-----------------------------------|-------------|------|
| Drain-source voltage | V _{DS} | 60 | V |
| Continuous drain current at T _{amb} =25°C | I _D | 115 | mA |
| Pulsed drain current | I _{DM} | 800 | mA |
| Gate-source voltage | V _{GS} | ±40 | V |
| Power dissipation at T _{amb} =25°C | P _{tot} | 330 | mW |
| Operating and storage temperature range | T _j , T _{stg} | -55 to +150 | °C |

Electrical characteristics (at T_{amb} = 25°C unless otherwise stated)

| Parameter | Symbol | Min. | Max. | Unit | Conditions |
|---|---------------------|------|------|------|--|
| Drain-source breakdown voltage | BV _{DSS} | 60 | | V | I _D = 10μA, V _{GS} =0V |
| Gate-source threshold voltage | V _{GS(th)} | 1 | 2.5 | V | I _D = 250μA, V _{DS} =V _{GS} |
| Gate-body leakage | I _{GSS} | | 10 | nA | V _{GS} =±20V, V _{DS} =0V |
| Zero gate voltage drain current | I _{DSS} | | 1 | μΑ | V _{DS} = 48V, V _{GS} =0V |
| | | | 500 | μΑ | V _{DS} = 48V, V _{GS} =0V, T=125°C |
| On-state drain current ^(a) | I _{D(on)} | 500 | | mA | V _{DS} = 25V, V _{GS} = 10V |
| Static drain-source on-state | V _{DS(on)} | | 3.75 | V | V _{GS} = 10V, I _D = 500mA |
| voltage ^(a) | | | 375 | mV | V _{GS} = 5V, I _D = 50mA |
| Static drain-source on-state | R _{DS(on)} | | 7.5 | Ω | V _{GS} = 10V, I _D = 500mA |
| resistance ^(a) | | | 7.5 | Ω | V _{GS} = 5V, I _D = 50mA |
| Forward transconductance ^{(a)(b)} | 9 _{fs} | 80 | | mS | V _{DS} = 25V, I _D = 500mA |
| Input capacitance ^(b) | C _{iss} | | 50 | pF | |
| Common source output capacitance ^(b) | C _{oss} | | 25 | pF | V _{DS} = 25V, V _{GS} =0V f=1MHz |
| Reverse transfer capacitance(b) | C _{rss} | | 5 | pF | |
| Turn-on time ^{(b)(c)} | t _(on) | | 20 | ns | V _{DD} ≈30V, I _D = 200mA, |
| Turn-off time ^{(b)(c)} | t _(off) | | 20 | ns | R_g =25 Ω , R_L =150 Ω |

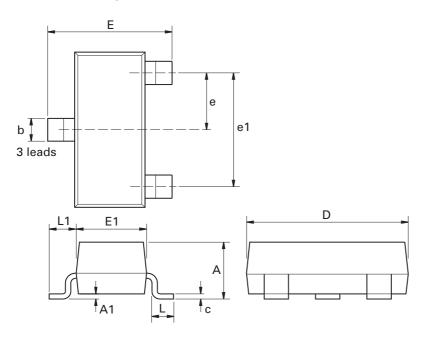
NOTES:

⁽a) Measured under pulsed conditions. Pulse width $\leq 300 \, \mu s$; duty cycle $\leq 2\%$.

⁽b) Sample test.

⁽c) Switching times measured with 50Ω source impedance and <5ns rise time on a pulse generator Spice parameter data is available upon request for this device.

SOT23 Package outline



| Dim. | Millin | neters | Inc | hes | Dim. | Millimeters | | Inches | |
|------|--------|--------|--------|-------|------|-------------|------|--------|--------|
| | Min. | Max. | Min. | Max. | | Min. | Max. | Min. | Max. |
| Α | - | 1.12 | - | 0.044 | e1 | 1.90 | NOM | 0.075 | NOM |
| A1 | 0.01 | 0.10 | 0.0004 | 0.004 | Е | 2.10 | 2.64 | 0.083 | 0.104 |
| b | 0.30 | 0.50 | 0.012 | 0.020 | E1 | 1.20 | 1.40 | 0.047 | 0.055 |
| С | 0.085 | 0.20 | 0.003 | 0.008 | L | 0.25 | 0.60 | 0.0098 | 0.0236 |
| D | 2.80 | 3.04 | 0.110 | 0.120 | L1 | 0.45 | 0.62 | 0.018 | 0.024 |
| е | 0.95 | NOM | 0.037 | NOM | - | - | - | - | - |

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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 - 1. are intended to implant into the body

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|-----------------------------------|---|
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| "Obsolete" | Production has been discontinued |
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